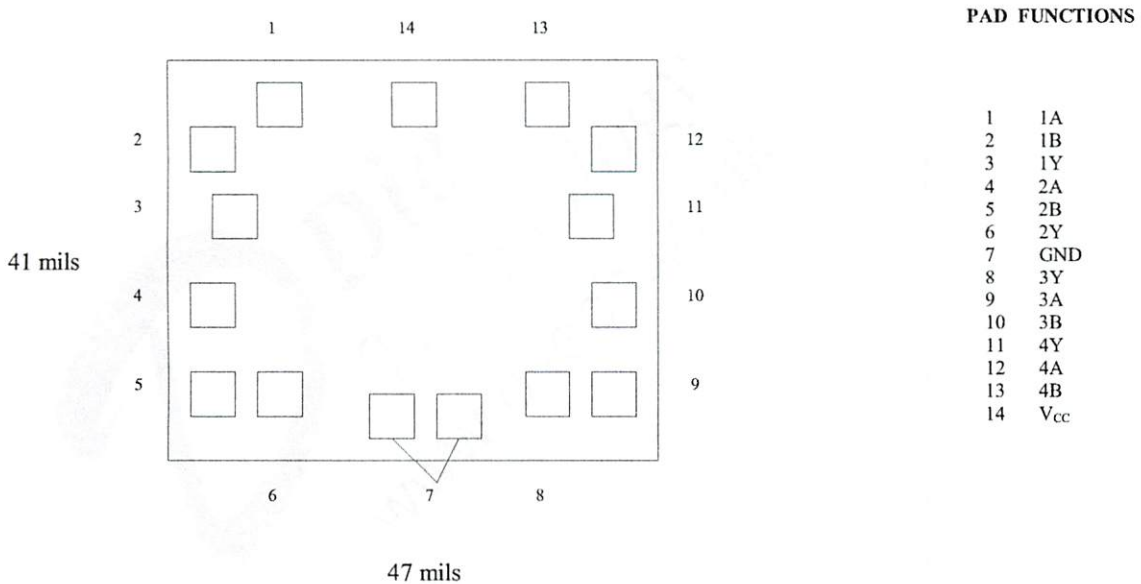


**Die Technology Ltd**  
 Corbrook Road, Chadderton,  
 Lancashire OL9 9SD England  
 Tel: +44(0)161 626 3827  
 Fax: +44(0)161 627 2341 Fax: +44(0)161 626 7668  
 Website: www.ditech.co.uk Email: sales@ditech.co.uk



Volume Semiconductor Supplier



The information given is believed to be correct at the time of issue.  
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.  
 Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

**Note: 1 mil = 0.001inch**

<p><u>APPROVED</u></p> <p>D Markham</p> <p>DATE: 18/8/00</p>	<p>5438</p> <p><b>TEXAS INSTRUMENTS</b></p>	<p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 47 x 41 x <del>25</del> 25</p> <p>BOND PADS (Mils): 4 x 4</p> <p>MASK. REF:</p> <p>GEOMETRY:</p> <p>BACK POTENTIAL: GND</p>
<p><u>SERIAL NUMBER</u></p> <p>004297</p>		<p><u>METALLISATION</u></p> <p>TOP: Al</p> <p>BACK: Si</p>